

PC827H



DESCRIPTION

The PC827H optically coupled isolator consist of an infrared light emitting diode and an NPN silicon photo transistor in a space efficient Dual In Line Plastic Package.

FEATURES

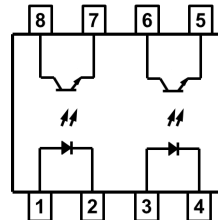
- AC Isolation Voltage 5300V_{RMS}
- CTR Selections Available
- Wide Operating Temperature Range
-30°C to +100°C
- Lead Free and RoHS Compliant
- UL File E91231 Package Code "EE"

APPLICATIONS

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedances

ORDER INFORMATION

- Add G after PN for 10mm lead spacing
- Add SM after PN for Surface Mount
- Add SMT&R after PN for Surface Mount Tape & Reel



1, 3	Anode
2, 4	Cathode
5, 7	Emitter
6, 8	Collector

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	50mA
Peak Forward Current (100µs, 100Hz)	1A
Reverse Voltage	6V
Power dissipation	70mW

Output

Collector to Emitter Voltage V _{CEO}	35V
Emitter to Collector Voltage V _{ECO}	6V
Collector Current	50mA
Power Dissipation	150mW

Total Package

Isolation Voltage	5300V _{RMS}
Total Power Dissipation	200mW
Operating Temperature	-30 to 100 °C
Junction Temperature	125 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	$I_F = 20\text{mA}$		1.2	1.4	V
Reverse Leakage	I_R	$V_R = 4\text{V}$			10	μA
Terminal Capacitance	C_t	$V = 0\text{V}, f = 1\text{KHz}$		30	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector–Emitter Breakdown Voltage	BV_{CEO}	$I_C = 0.1\text{mA}, I_F = 0\text{mA}$	35			V
Emitter–Collector Breakdown Voltage	BV_{ECO}	$I_E = 10\mu\text{A}, I_F = 0\text{mA}$	6			V
Collector–Emitter Dark Current	I_{CEO}	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$			100	nA

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ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	50		600	%
		Optional CTR Grades				
		GB	100		600	
		BL	200		600	
		GR	100		300	
		A	80		160	
		B	130		260	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_F = 20\text{mA}, I_C = 1\text{mA}$		0.1	0.2	V
Floating Capacitance	C_f	$V = 0\text{V}, f = 1\text{MHz}$		0.6	1	pF
Cut-Off Frequency	f_c	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$		80		kHz
Output Rise Time	t_r	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$		4	18	μs
Output Fall Time	t_f			3	18	

ISOLATION

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Input to Output Isolation Voltage	V_{ISO}	AC 1 minute, RH = 40% to 60% Note 1	5300			V_{RMS}
Input to Output Isolation Resistance	R_{ISO}	$V_{IO} = 500\text{V}, \text{RH} = 40\% \text{ to } 60\%$ Note 1	5×10^{10}	1×10^{11}		Ω

Note 1 : Measure with input leads shorted together and output leads shorted together.

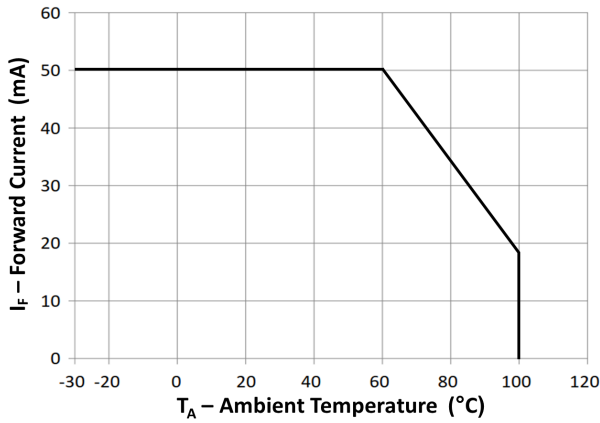


Fig 1 Forward Current vs Ambient Temperature

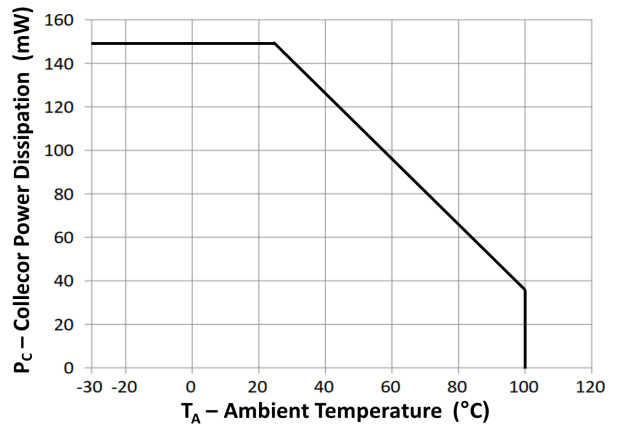


Fig 2 Collector Power Dissipation vs Ambient Temperature

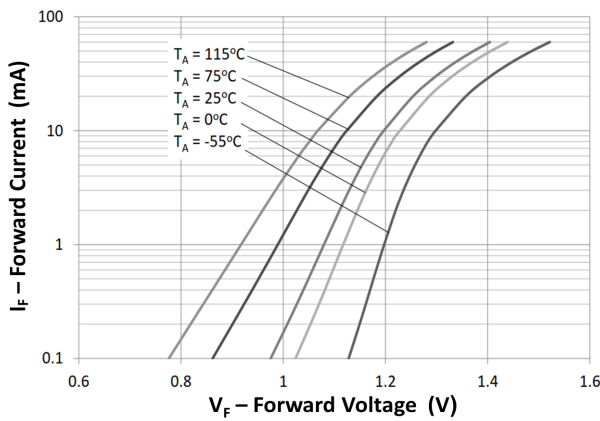


Fig 3 Forward Current vs Forward Voltage

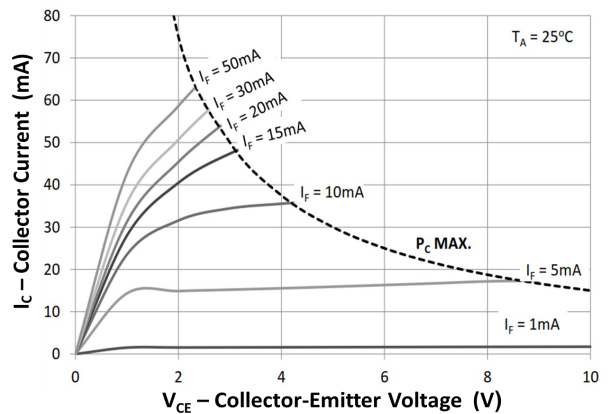


Fig 4 Collector Current vs Collector-Emitter Voltage

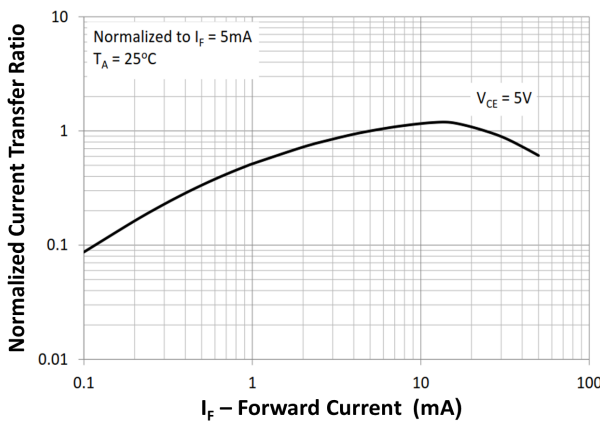


Fig 5 Normalized Current Transfer Ratio vs Forward Current

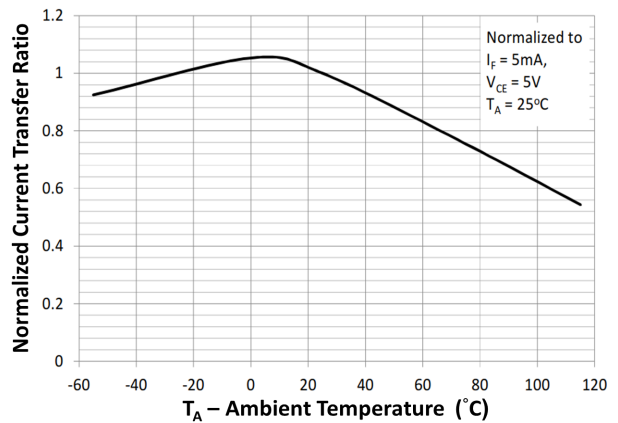


Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature

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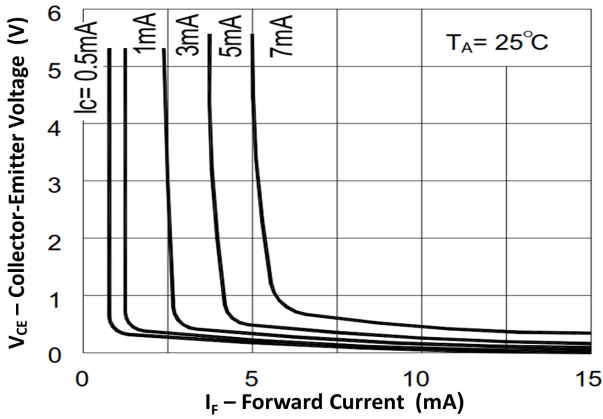


Fig 7 Collector-Emitter Voltage vs Forward Current

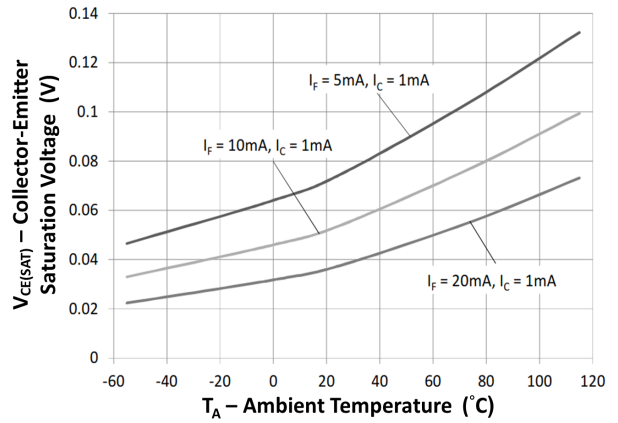


Fig 8 Collector-Emitter Saturation Voltage vs Ambient Temperature

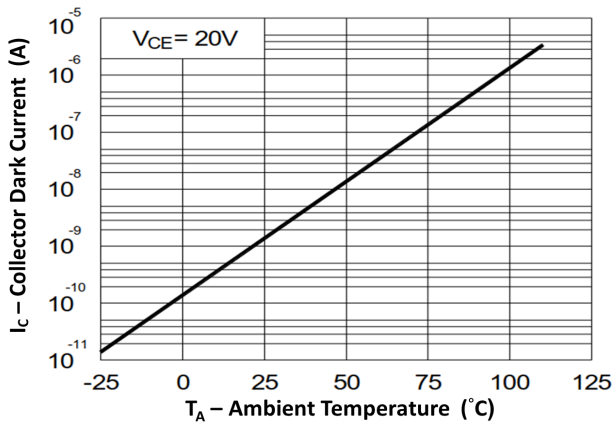


Fig 9 Collector Dark Current vs Ambient Temperature

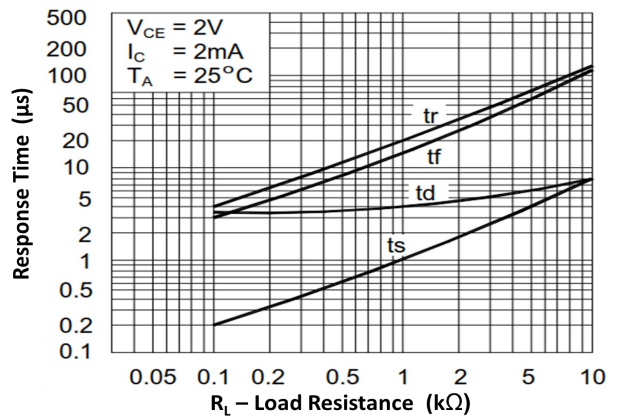


Fig 10 Response Time vs Load Resistance

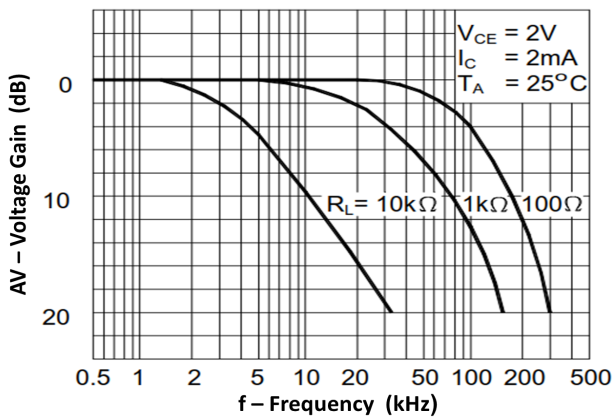
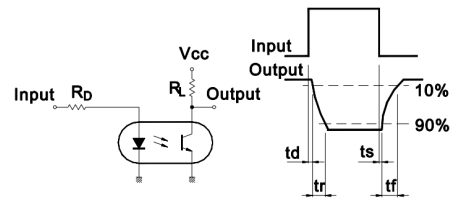
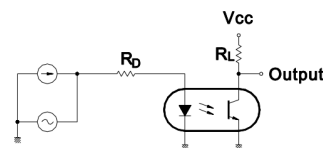


Fig 11 Frequency Response



Response Time Test Circuit



Frequency Response Test Circuit

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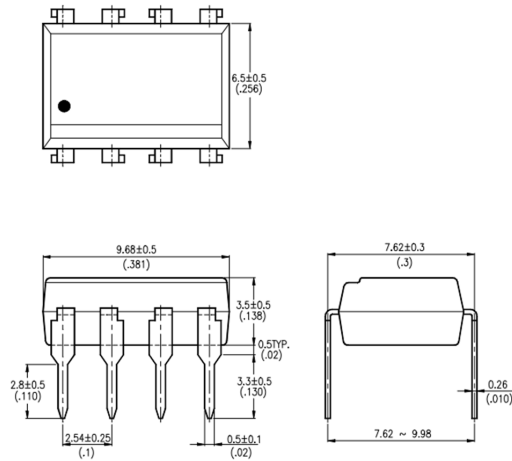
ORDER INFORMATION

PC827H (UL Approval)			
After PN	PN	Description	Packing Quantity
None	PC827H, PC827HGB, PC827HBL, PC827HGR, PC827HA, PC827HB, PC827HC, PC827HD	Standard DIP8	50 pcs per tube
G	PC827HG, PC827HGBG, PC827HBLG, PC827HGRG, PC827HAG, PC827HBG, PC827HCG, PC827HDG	10mm Lead Spacing	50 pcs per tube
SM	PC827HSM, PC827HGBSM, PC827HBLSM, PC827GRSM, PC827HASM, PC827HBSM, PC827HCSM, PC827HDSM	Surface Mount	50 pcs per tube
SMT&R	PC827HSMT&R, PC827HGBSMT&R, PC827HGRSMT&R, PC827HBSMT&R, PC827HASMT&R, PC827HBSMT&R, PC827HCSMT&R, PC827HDSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

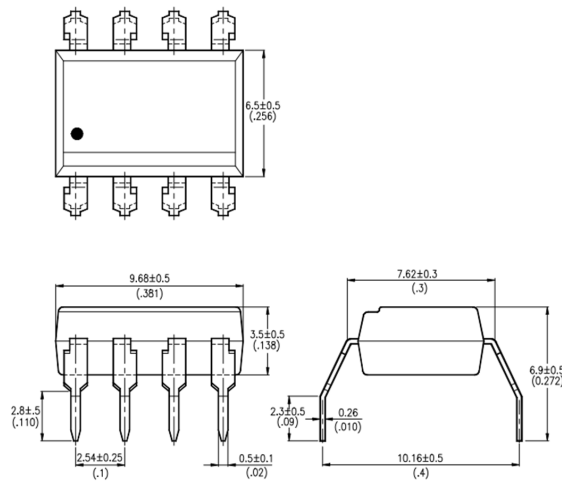
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PACKAGE DIMENSIONS in mm (inch)

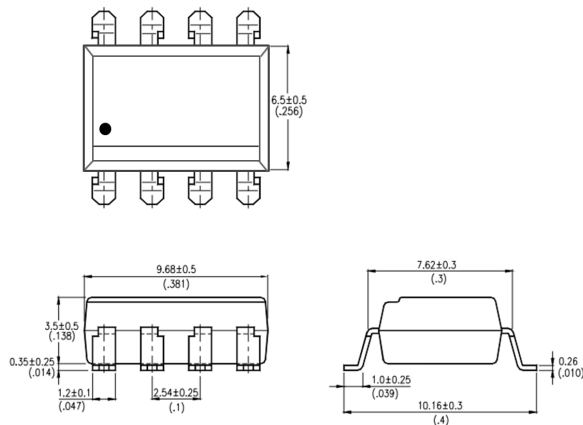
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PC827HG

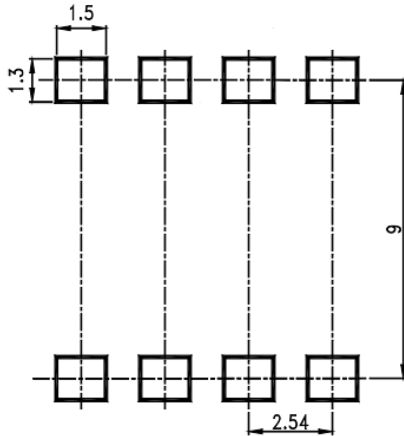


PC827HSM

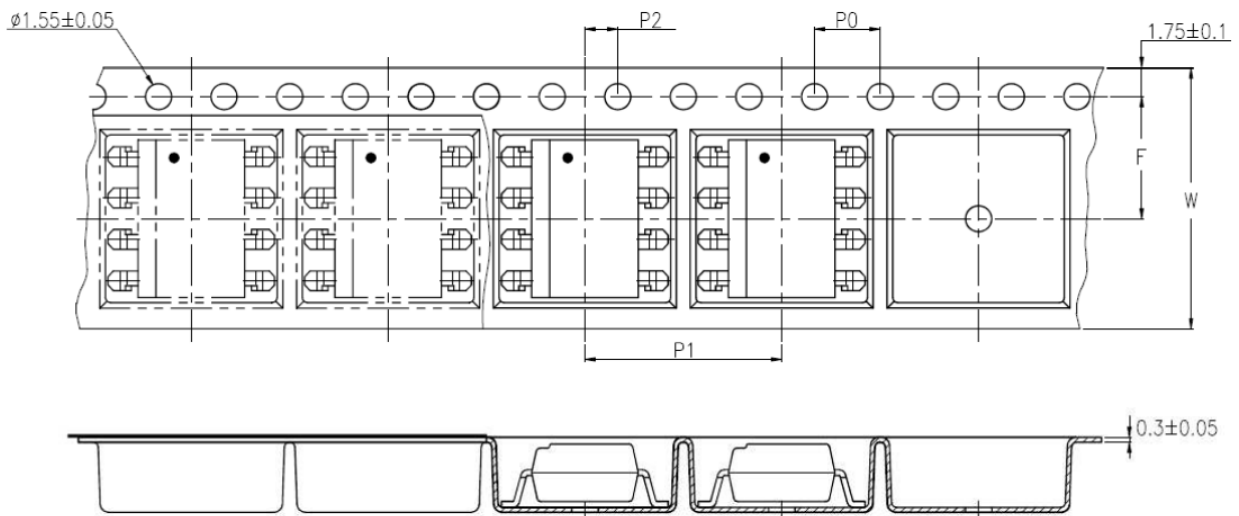


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RECOMMENDED PAD LAYOUT FOR SMD (mm)

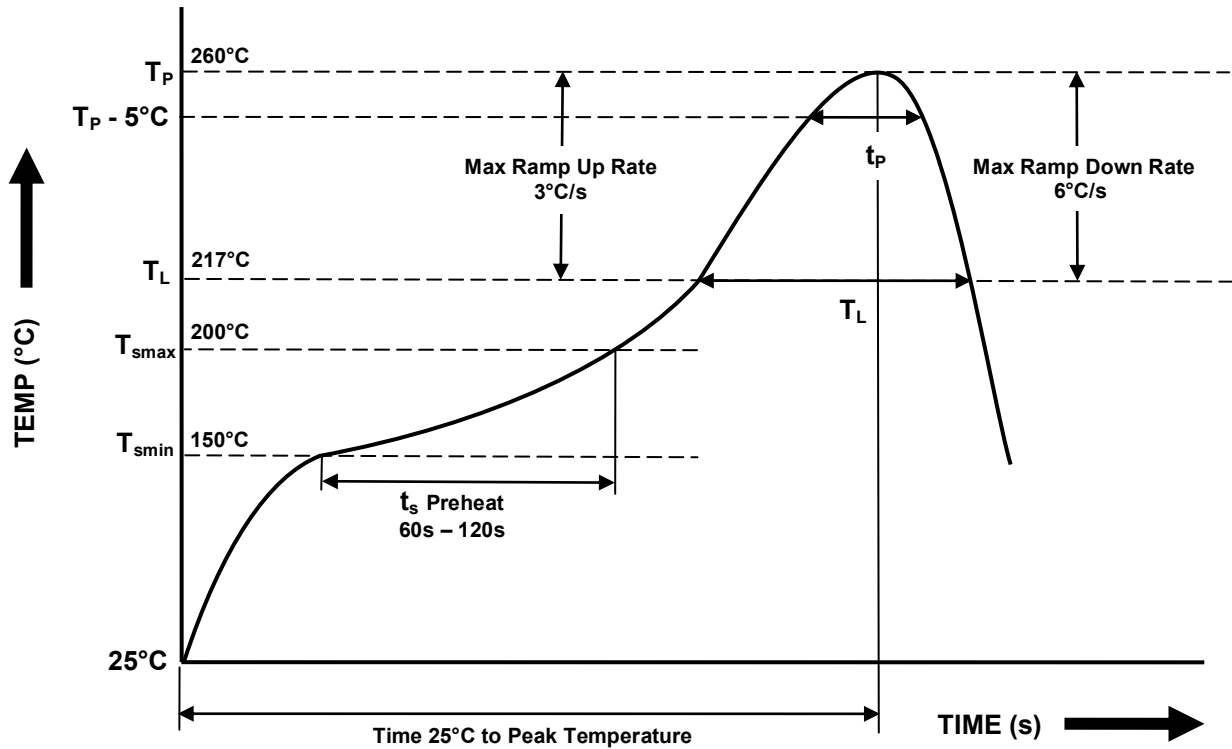


TAPE AND REEL PACKAGING



Description	Symbol	Dimension mm (inch)
Tape Width	W	16 ± 0.3 (0.63)
Pitch of Sprocket Holes	P ₀	4 ± 0.1 (0.15)
Distance of Compartment to Sprocket Holes	F	7.5 ± 0.1 (0.295)
	P ₂	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P ₁	12 ± 0.1 (0.472)

IR REFLOW SOLDERING TEMPERATURE PROFILE FOR SMD
One Time Reflow Soldering is Recommended.
Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat <ul style="list-style-type: none"> - Min Temperature (T_{SMIN}) - Max Temperature (T_{SMAX}) - Time T_{SMIN} to T_{SMAX} (t_s) 	150°C 200°C 60s - 120s
Soldering Zone <ul style="list-style-type: none"> - Peak Temperature (T_P) - Time at Peak Temperature - Liquidous Temperature (T_L) - Time within 5°C of Actual Peak Temperature ($T_P - 5^\circ\text{C}$) - Time maintained above T_L (t_L) - Ramp Up Rate (T_L to T_P) - Ramp Down Rate (T_P to T_L) 	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T_{smax} to T_P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max

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